

C0603C821J2TACTU

General Information

Series

Style

Description

Features

Aliases (C0603C821J2TAC7867)
SMD Comm X8G HT150C Ceramic 820 pF 5% 200 VDC X8

SMD Comm X8G HT150C, Ceramic, 820 pF, 5%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm

SMD Comm X8G HT150C

SMD, MLCC, High Temperature,

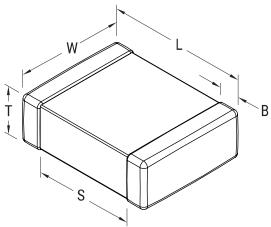
High Temperature, Ultra-Stable

SMD Chip

Ultra-Stable

Yes
Tin
No
No
3.7 mg
78 Weeks

1



	<u> </u>		RoHS
			Termination
			Marking
	s	AEC-Q200	
		Click here for the 3D model.	Typical Component Weight
	Click here for		Shelf Life
			MSL
	Dimensions		Specifications
	Chip Size	0603	Capacitance
	L	1.6mm +/-0.15mm	Measurement Condition

Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

Packaging Specifications		
Packaging	T&R, 180mm, Paper Tape	
Packaging Quantity	4000	

Specifications	
Capacitance	820 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	5%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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